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January 2015

FDMC86260ET150

N-Channel Power Trench[®] MOSFET 150 V, 25 A, 34 m Ω

Features

- Extended T_J rating to 175°C
- Max $r_{DS(on)}$ = 34 m Ω at V_{GS} = 10 V, I_D = 5.4 A
- Max $r_{DS(on)}$ = 44 m Ω at V_{GS} = 6 V, I_D = 4.8 A
- High performance technology for extremely low r_{DS(on)}
- 100% UIL Tested
- Termination is Lead-free
- RoHS Compliant



Bottom

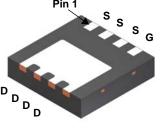
General Description

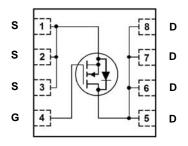
This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Application

■ DC-DC Conversion







Top Power 33

MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol		Parameter				Units
V _{DS}	Drain to Source \	/oltage			150	V
V _{GS}	Gate to Source V	/oltage			±20	V
	Drain Current	-Continuous	T _C = 25 °C	(Note 5)	25	
		-Continuous	T _C = 100 °C	(Note 5)	18	۸
ID.		-Continuous	T _A = 25 °C	(Note 1a)	5.4	A
		-Pulsed		(Note 4)	116	
E _{AS}	Single Pulse Ava	lanche Energy		(Note 3)	121	mJ
P_{D}	Power Dissipatio	n	T _C = 25 °C		65	W
	Power Dissipation	n	T _A = 25 °C	(Note 1a)	2.8	VV
T _J , T _{STG}	Operating and St	orage Junction Temperat	ure Range		-55 to +175	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	2.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	53	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC86260ET	FDMC86260ET150	Power33	13 "	12 mm	3000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		110		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 120 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	2.7	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-9		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 5.4 \text{ A}$		27	34	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 4.8 \text{ A}$		31	44	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 5.4 \text{ A}, T_J = 125 ^{\circ}\text{C}$		55	69	
g _{FS}	Forward Transconductance	$V_{DD} = 10 \text{ V}, I_D = 5.4 \text{ A}$		19		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 75 V V 0 V		1000	1330	pF
Coss	Output Capacitance	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$		105	140	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1/11/12		4.8	10	pF
R_g	Gate Resistance		0.1	0.6	1.8	Ω

Switching Characteristics

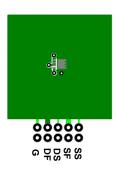
t _{d(on)}	Turn-On Delay Time		9.5	19	ns
t _r	Rise Time	V _{DD} = 75 V, I _D = 5.4 A,	2	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	17	30	ns
t _f	Fall Time		3.3	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V _{GS} = 0 V to 10 V	15	21	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to 6 V}$ $V_{DD} = 75 \text{ V},$	9.7	14	nC
Q_{gs}	Total Gate Charge	I _D = 5.4 A	4.0		nC
Q _{gd}	Gate to Drain "Miller" Charge		3.1		nC

Drain-Source Diode Characteristics

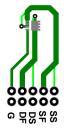
V	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 5.4 \text{ A}$	(Note 2)	0.77	1.3	V
v SD	V _{SD} Source to Drain Diode Forward voltage	$V_{GS} = 0 \text{ V}, I_{S} = 1.9 \text{ A}$	(Note 2)	0.72	1.2	V
t _{rr}	Reverse Recovery Time	L = 5.4 A di/dt = 100 A/r		64	102	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 5.4 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s}$		85	137	nC

Notes

^{1.} R_{0,1A} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0CA} is determined by the user's board design.



a. 53 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 125 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.
- 3. E_{AS} of 121 mJ is based on starting T_J = 25 $^{\circ}$ C, L = 3 mH, I_{AS} = 9 A, V_{DD} = 150 V, V_{GS} = 10 V. 100% test at L = 0.1 mH, I_{AS} = 22 A.
- 4. Pulsed Id please refer to Fig 11 SOA graph for more details.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

Typical Characteristics T_J = 25 °C unless otherwise noted

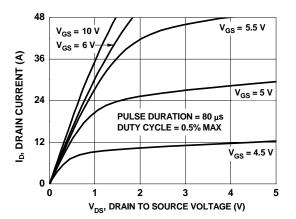


Figure 1. On-Region Characteristics

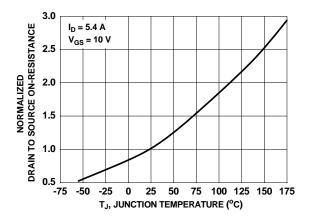


Figure 3. Normalized On-Resistance vs Junction Temperature

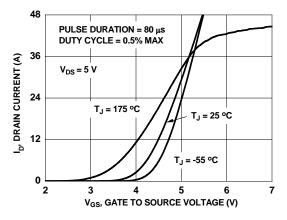


Figure 5. Transfer Characteristics

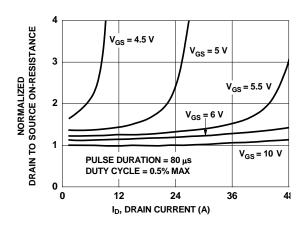


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

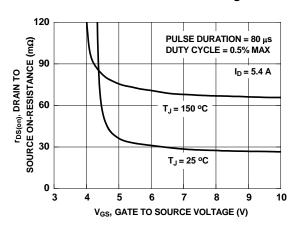


Figure 4. On-Resistance vs Gate to Source Voltage

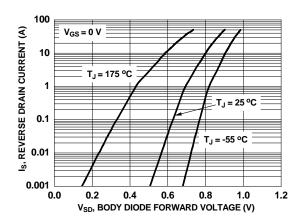


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

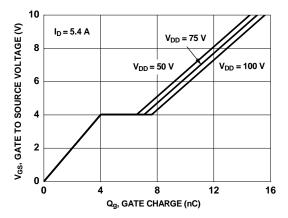


Figure 7. Gate Charge Characteristics

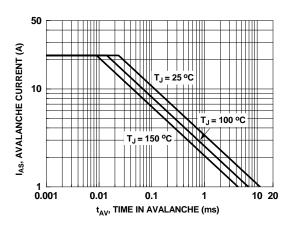


Figure 9. Unclamped Inductive Switching Capability

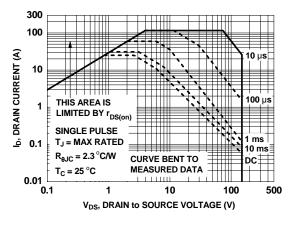


Figure 11. Forward Bias Safe Operating Area

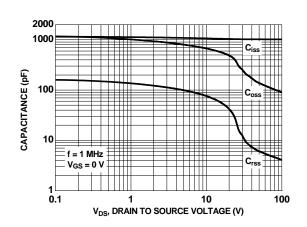


Figure 8. Capacitance vs Drain to Source Voltage

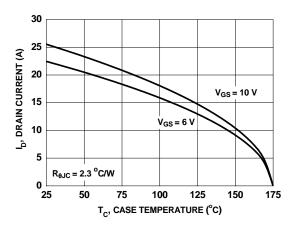


Figure 10. Maximum Continuous Drain Current vs Case Temperature

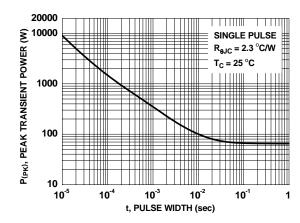


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted

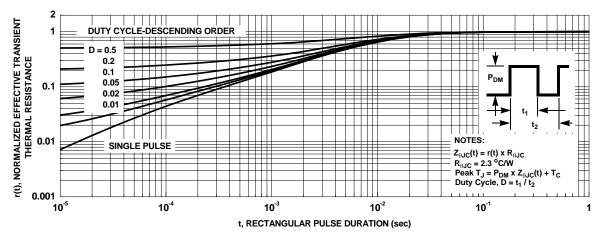
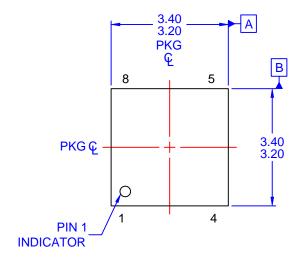
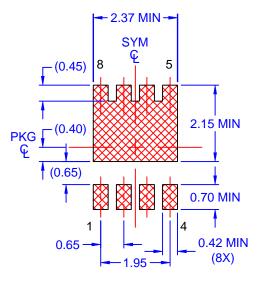
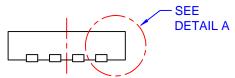


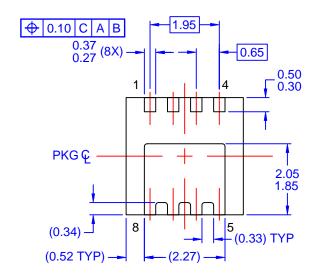
Figure 13. Junction-to-Case Transient Thermal Response Curve





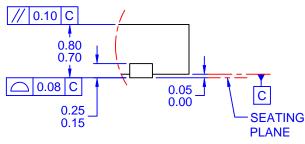


LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA, DATED OCTOBER 2002.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: PQFN08HREV1



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